comprises a plurality of pads extending laterally out from the pair of rails, and wherein the wafer cushion seats on a floor of the base portion by way of the plurality of pads and each of the pads has a top surface and when the cassette is positioned in the base portion, the feet of the cassette seat on top of the pads whereby the pads are sandwiched between the base portion floor and the cassette.

10. A method of protecting thin wafers in an H-bar cassette during shipment, the H-bar wafer cassette having a plurality of slots with each slot having a rigid edge portion at the bottom of the slot, the method comprising:

raising the wafers out of contact with the cassette by suspending the wafers between a row of end suspended upper arcuate wafer engagement portions engaging an arcuate edge portion centered about top dead center of the wafers and a row of end suspended lower arcuate wafer engagement portions engaging an arcuate edge portion centered about the bottom top dead center of the wafers;

spacing the wafers from the cassette such that there is a predetermined radial gap between each of the wafers and each respective rigid edge portion and positioning ~~the~~ a lower cushion such that there is a predetermined circumferential gap between the end of each lower arcuate wafer engagement portion and the rigid edge portion; and providing one or both of the following steps:

providing further a pair of rows of rigid upper arcuate support portions, each arcuate support portion spaced from an end of the end suspended upper arcuate wafer engagement portions, the positioning of the pair of rows of rigid upper arcuate support portions in substantial vertical alignment with the rigid edge portions, and

providing a pair of rows of prongs extending from ~~the top cover~~ a top cushion positioned for extending intermediate adjacent wafers, each row of prongs in vertical alignment with one of the respective rows of rigid edge portions.

11. The method of claim 10 further comprising providing a gap between the wafers and the rows of rigid upper arcuate support portions such that the wafers during shipment do not contact the rigid upper arcuate support portions and do not contact the rigid edge portions except in a shock condition.